

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Eun Sang LEE	09/15/2006
Jong Goo WON	09/15/2006
Jung Talk LEE	09/15/2006
RECEIVING PARTY DATA	
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City:	Incheon
State/Country:	KOREA, REPUBLIC OF
Postal Code:	402-751
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11532134
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ATTORNEY DOCKET NUMBER:	0005474.0005
NAME OF SUBMITTER:	Adam K Sacharoff

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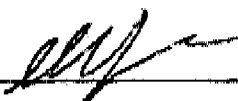
PATENT  
REEL: 018256 FRAME: 0793

Total Attachments: 3  
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source=Assignments#page3.tif

**PATENT ASSIGNMENT****TITLE OF INVENTION: MOVING HEAD FOR SEMICONDUCTOR WAFER POLISHING APPARATUS**

The Assignor(s) having made the above invention and filed provisional application for within the United States thereon, and the Assignee being desirous of acquiring the same; in consideration of and in exchange for the sum of One Dollar (\$1.00) and other good and valuable consideration, of the Assignor(s) hereby assigns to the Assignee, including its successors, assigns, heirs, administrators, all of the Assignor(s)' right, title and interest in and to the invention and the patent application therefor identified herein and to any and all patents which may evolve therefrom:

The Assignor(s) agrees to execute any papers or perform any acts required to establish, vest or protect the Assignee's rights therein or required by Assignee to obtain said patent, without any additional payment therefor, but without any expense to Assignors.

**ASSIGNEE: INHA-INDUSTRY PARTNERSHIP INSTITUTE**[Print or Type Name]**Address: Inha University, #253, Yonghyeon-dong, Nam-gu, Incheon 402-751****INVENTOR/ASSIGNOR: LEE, Eun Sang**[Print or Type Name]**Domicile/Residence: #103-101, Hyundai Apt., Cheonghak-dong, Yeonsu-gu, Incheon 406-702****Signature****Date**Sept - 15 - 2006

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ASSIGNEE: INHA-INDUSTRY PARTNERSHIP INSTITUTE

[Print or Type Name]

Address: Inha University, #253, Yonghyeon-dong, Nam-gu, Incheon 402-751INVENTOR/ASSIGNOR: LEE, Jung Taik

[Print or Type Name]

Domicile/Residence: \_\_\_\_\_

Signature: \_\_\_\_\_



Date: \_\_\_\_\_

2006. sept. 15th

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**ASSIGNEE: INHA-INDUSTRY PARTNERSHIP INSTITUTE**[Print or Type Name]**Address: Inha University, #253, Yonghyeon-dong, Nam-gu, Incheon 402-751****INVENTOR/ASSIGNOR: WON, Jong Goo**[Print or Type Name]**Dom/dle/Residence:** \_\_\_\_\_**Signature:** \_\_\_\_\_**Date:** 2006.9.15**PATENT****RECORDED: 09/15/2006****REEL: 018256 FRAME: 0797**